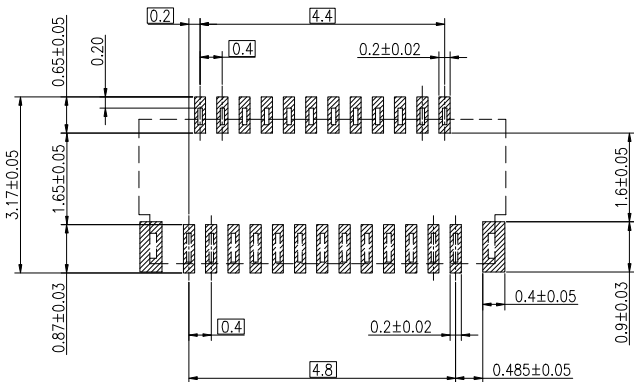
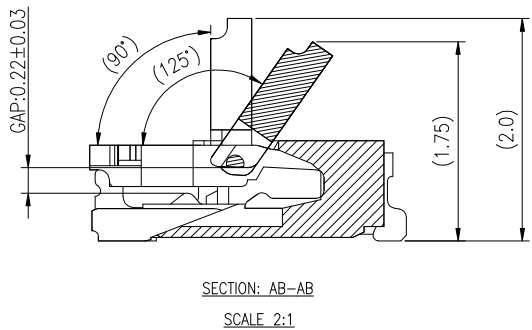
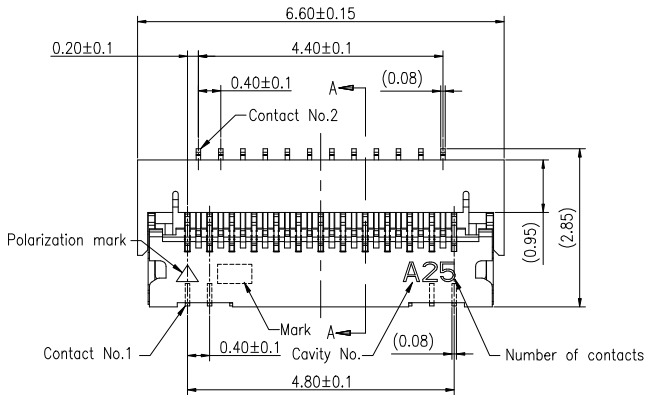
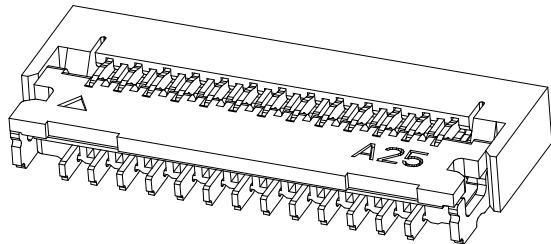
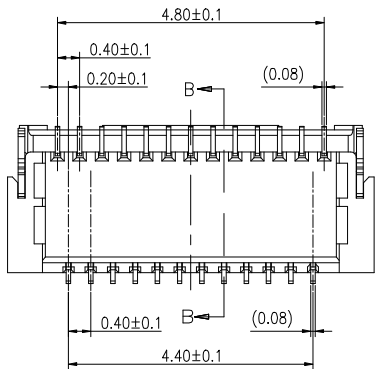
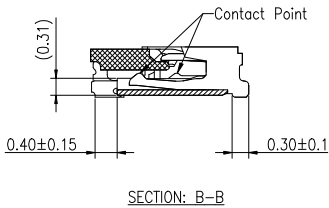
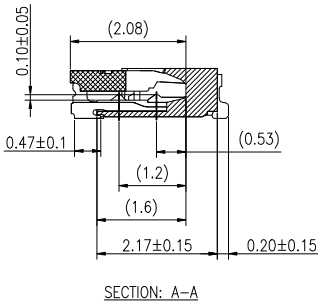
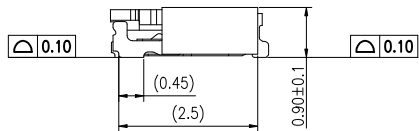
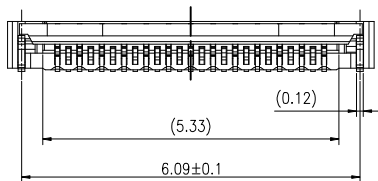


REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A			NEW DRAWING		



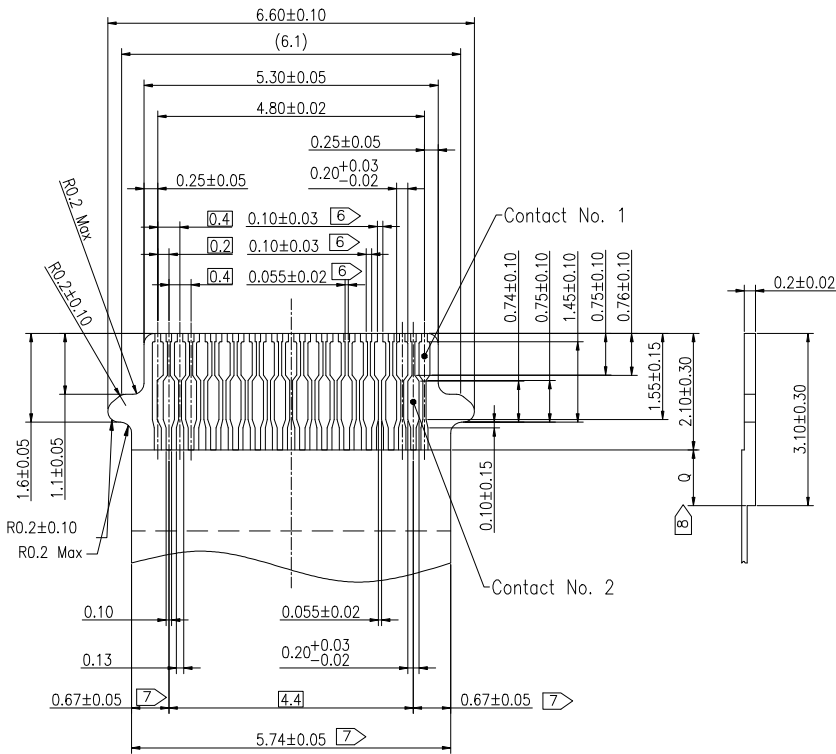
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05 / THICKNESS T=0.10mm



3D VIEW

DESIGN:		Xiping Huang			广东国连电子有限公司			
CHECK:		Ke Tian			GUANGDONG GUOLIAN ELECTRONICS CO.,LTD			
APPROVED:		Youquan Xu			TITLE:			
DIM	TOL	DIM	TOL	0.2翻盖H0.9				
X.	±0.25			PART NO.				
X.X	±0.20	X°.	±3.0°	C0209-xx-21LR1				
X.XX	±0.15	X.X°						
		X.XX°						
X.XXX		X.XXX°		REV. A	SCALE: N/A	UNIT: mm	SHEET: 1/1	

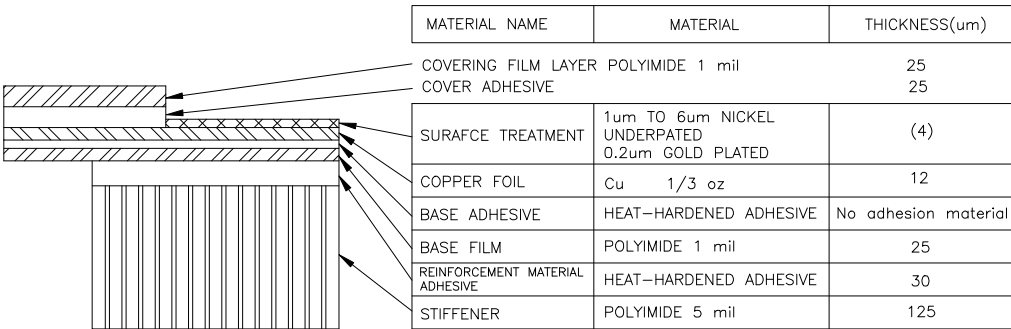
REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A			NEW DRAWING		



RECOMMENDED FPC 1:1

NOTE: [6] Shows recommended dimension when lead for plating is required.
[7] Indicated tolerance is applicable to the exposed conductor.
[8] Dimenton Q must be 0.5mm minimum.

FPC CONFIGURATION (REFERENCE EXAMPLE) (FREE)



DESIGN:		Xiping Huang			广东国连电子有限公司			
CHECK:		Ke Tian			GUANGDONG GUOLIAN ELECTRONICS CO.,LTD			
APPROVED:		Youquan Xu			TITLE:			
DIM	TOL	DIM	TOL	0.2翻盖H0.9				
X.	±0.25	X° X.X° X.XX° X.XXX°	±3.0°	PART NO. C0209-xx-21LR1				
X.X	±0.20							
X.XX	±0.15							
X.XXX								
				REV. A	SCALE: N/A	UNIT: mm	SHEET: 1/1	